

SE40120A
N-Channel Enhancement-Mode MOSFET

Revision: A

General Description

Thigh Density Cell Design For Ultra Low On-Resistance Fully Characterized Avalanche Voltage and Current Improved Shoot-Through FOM

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

Features

For a single MOSFET

- $V_{DS} = 40V$
- $R_{DS(ON)} = 3.2m\Omega @ V_{GS}=10V$

Pin configurations

See Diagram below



Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	Continuous	I_D	A
Pulsed			
Single Pulse Avalanche Energy	E_{AS}	1080	mJ
Peak Diode Recovery	dv/dt	5	V/ns
Total Power Dissipation @ $T_A=25^\circ C$	P_D	130	W
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Resistance

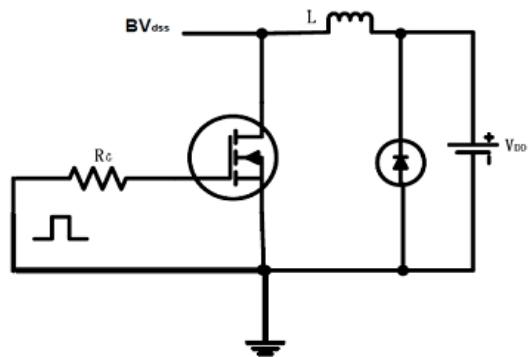
Symbol	Parameter	TO-220	Units
$R_{\theta JC}$	Junction to Case	0.6	°C/W
$R_{\theta JA}$	Junction to Ambient ($t \leq 10s$)	60	°C/W

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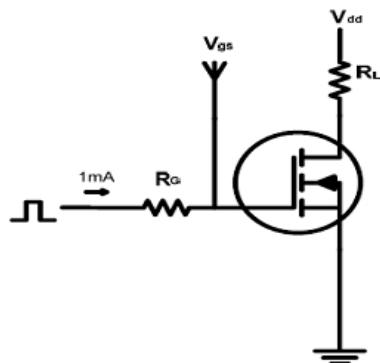
Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250µA, V _{GS} =0 V	40	45		V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =40 V, V _{GS} =0 V			1	µA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =20 V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250µA	1.2		2.5	V
R _{DSON}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A		3.2	4.0	mΩ
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, f=1MHz		5400		pF
C _{oss}	Output Capacitance			970		pF
C _{rss}	Reverse Transfer Capacitance			380		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge ²	V _{GS} =10V, V _{DS} =80V, I _D =20A		68		nC
Q _{gs}	Gate Source Charge			17		nC
Q _{gd}	Gate Drain Charge			16		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =80V, R _{GEN} =3.9Ω I _D =20A		15		ns
t _{d(off)}	Turn-Off Delay Time			52		ns
t _{d(r)}	Turn-On Rise Time			18		ns
t _{d(f)}	Turn-Off Fall Time			23		ns

Test Circuits and Waveform

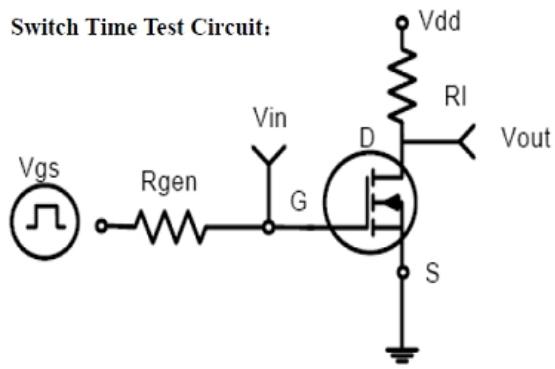
EAS test circuits:



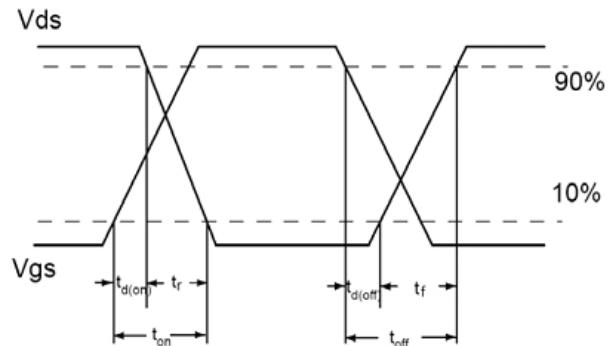
Gate charge test circuit:



Switch Time Test Circuit:



Switch Waveforms:



Typical Characteristics

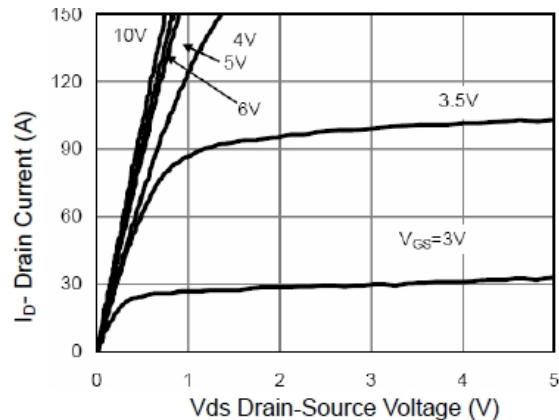


Figure 1 Output Characteristics

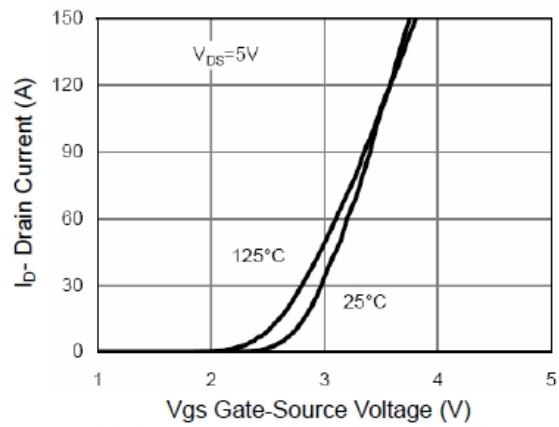


Figure 2 Transfer Characteristics

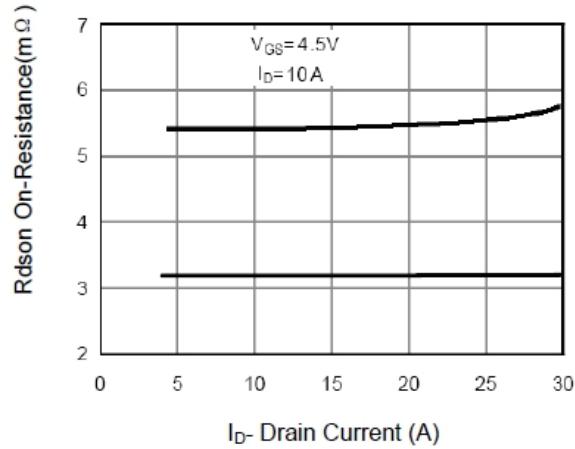


Figure 3 R_{dson}- Drain Current

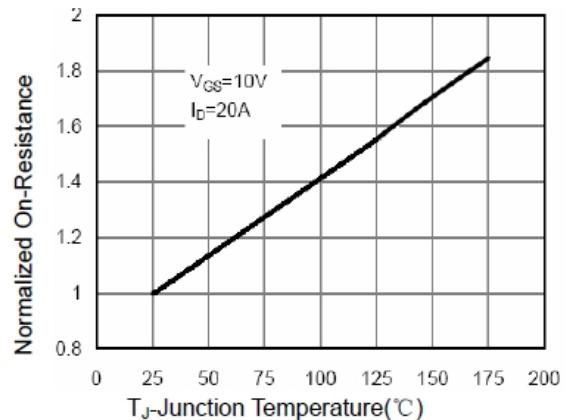


Figure 4 R_{dson}-JunctionTemperature

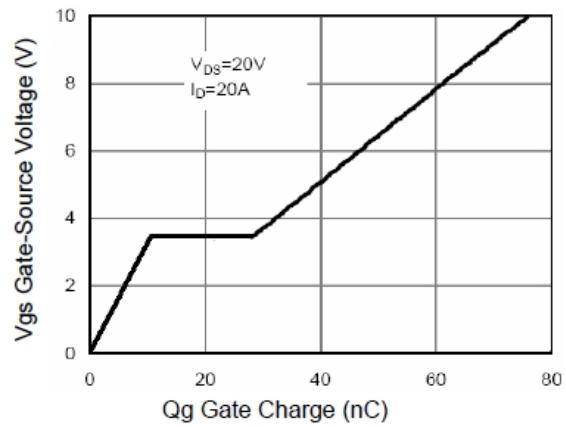


Figure 5 Gate Charge

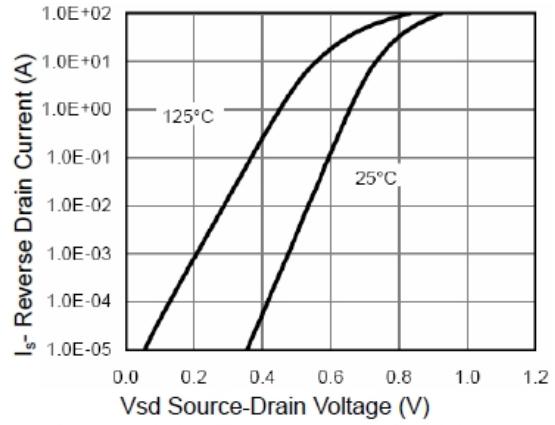


Figure 6 Source- Drain Diode Forward

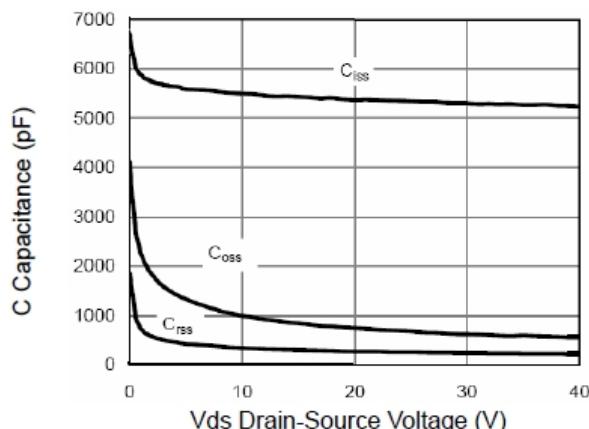


Figure 7 Capacitance vs Vds

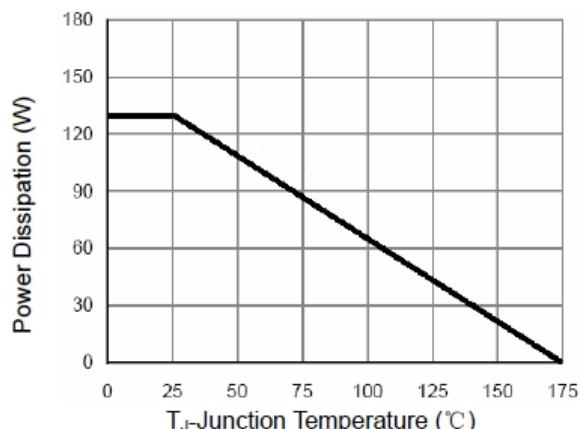


Figure 9 Power De-rating

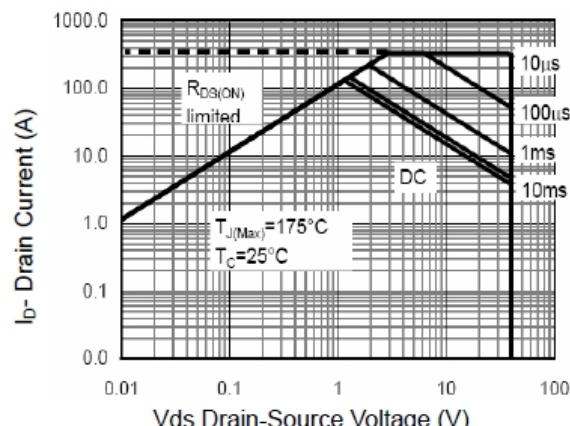


Figure 8 Safe Operation Area

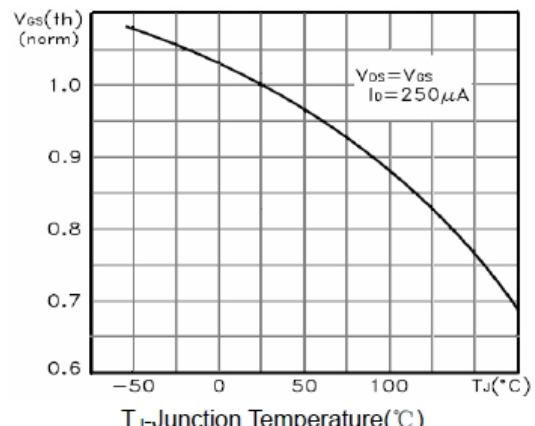


Figure 10 V_{GS(th)} vs Junction Temperature

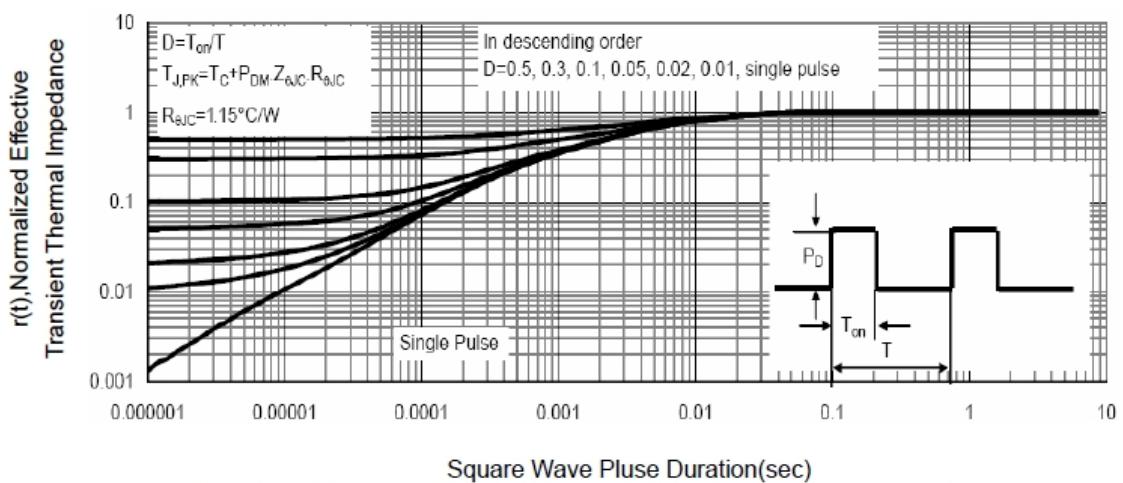
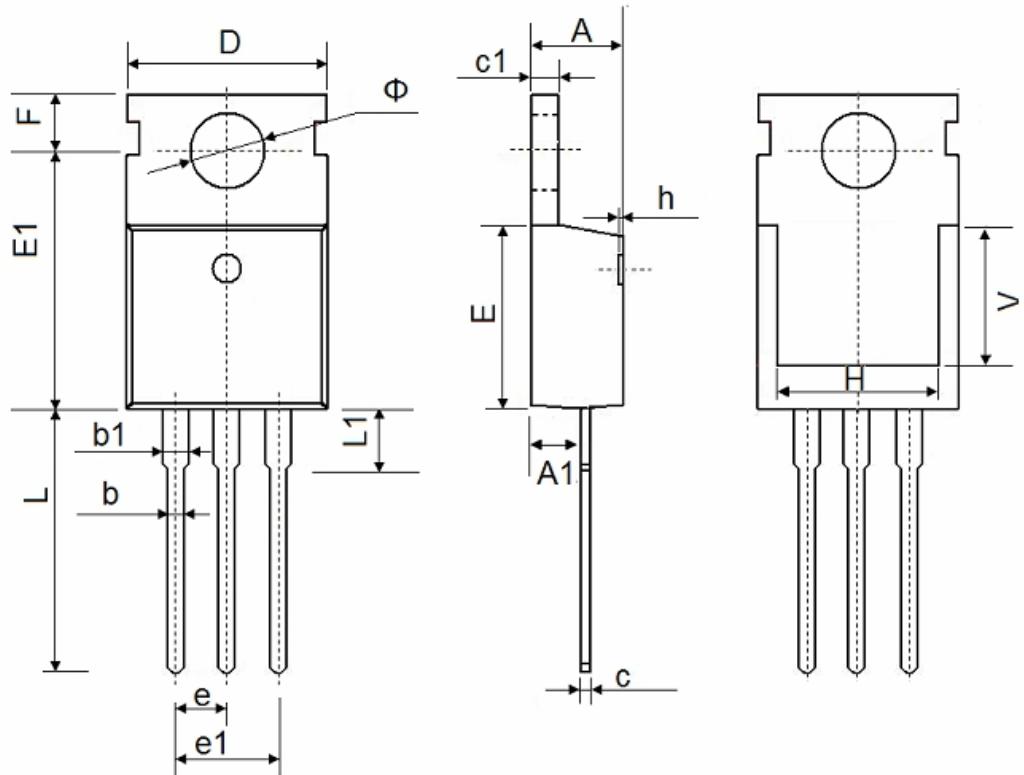


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Outline Dimension

TO-220



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

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